



Features

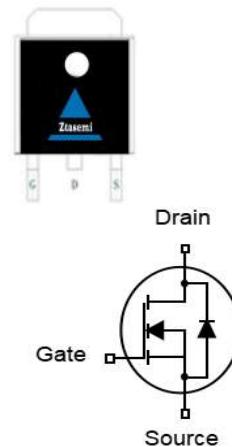
- N-Channel
- Low Crss
- Very low on -resistance RDS(ON)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 100% EAS Tested



Part ID	Package Type	Marking	Packing
ZT045N04D	TO-252	ZT045N04D	2500pcs/reel

V_{DS}	40	V
$R_{DS(on),TYP}$ @ $V_{GS}=10\text{ V}$	4.5	$\text{m}\Omega$
$R_{DS(on),TYP}$ @ $V_{GS}=4.5\text{ V}$	6.0	$\text{m}\Omega$
I_D	80	A

TO-252



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
Common Ratings (Tc=25°C Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	± 20	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	40	V
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c = 25^\circ\text{C}$	A
Mounted on Large Heat Sink			
I_D	Drain Current-Continuous	$T_c = 25^\circ\text{C}$	A
		$T_c = 100^\circ\text{C}$	A
P_D	Maximum Power Dissipation	77	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.95	$^\circ\text{C}/\text{W}$
Drain-Source Avalanche Ratings			
EAS	Avalanche Energy, Single Pulsed (Note 2)	104	mJ



Electrical Characteristics ($T_j=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	40	--	--	V
Idss	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}, V_{GS}=0\text{V}$	--	--	1	μA
IGSS	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	± 100	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.4	2.1	V
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$	--	4.5	5.8	$\text{m}\Omega$
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=4.5\text{V}, I_D=20\text{A}$	--	6.0	10	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
Ciss	Input Capacitance	$V_{DS}=20\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	2953	--	pF
Coss	Output Capacitance		--	386	--	pF
Crss	Reverse Transfer Capacitance		--	232	--	pF
Rg	Gate Resistance	f=1MHz	--	1.7	--	Ω
Qg	Total Gate Charge	$V_{DS}=20\text{V}, I_D=30\text{A}, V_{GS}=10\text{V}$	--	56	--	nC
Qgs	Gate-Source Charge		--	9	--	nC
Qgd	Gate-Drain Charge		--	11	--	nC
Switching Characteristics						
Td(on)	Turn-on Delay Time	$V_{DS}=20\text{V}, I_D=30\text{A}, R_G=3.0\Omega, V_{GS}=10\text{V}$	--	8	--	ns
Tr	Turn-on Rise Time		--	18	--	ns
Td(off)	Turn-Off Delay Time		--	24	--	ns
Tf	Turn-Off Fall Time		--	14	--	ns
Source- Drain Diode Characteristics@ $T_j = 25^\circ\text{C}$ (unless otherwise stated)						
IS	Diode Forward Current		--	--	80	A
VSD	Forward on voltage (Note 3)	$I_S=20\text{A}, V_{GS}=0\text{V}$	--	--	1.2	V
Trr	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_F = 20\text{A}, \frac{di}{dt}=100\text{A}/\mu\text{s}$	--	22	--	ns
Qrr	Reverse Recovery Charge		--	11	--	nC

Notes:

- Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- EAS condition: $T_j = 25^\circ\text{C}$, $V_{DD} = 20\text{V}$, $V_G = 10\text{V}$, $R_G = 25\Omega$, $L = 0.5\text{mH}$.
- Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$



N- Channel Typical Characteristics

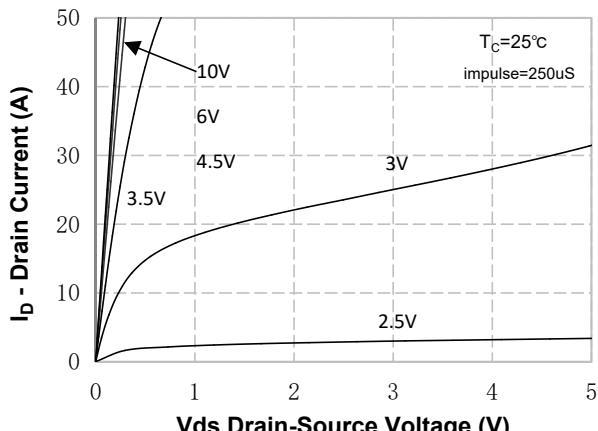


Figure 1. On-Region Characteristics

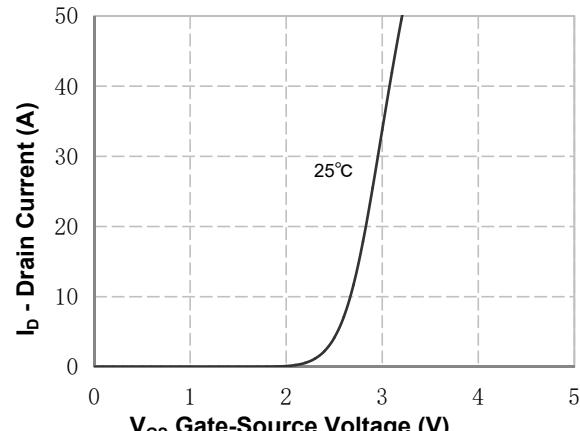


Figure 4. Transfer Characteristics

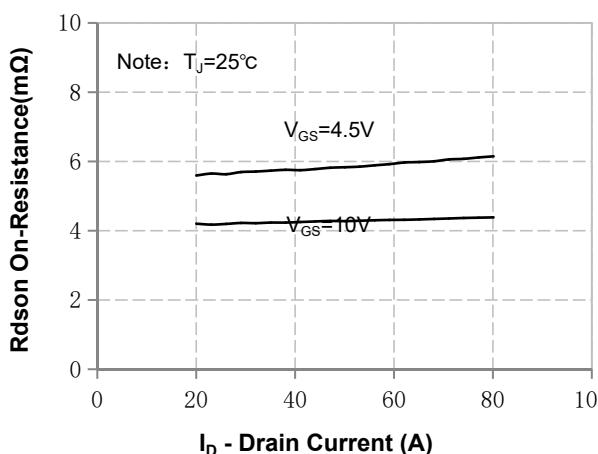


Figure 2. On-Resistance Variation vs Drain Current and Gate Voltage

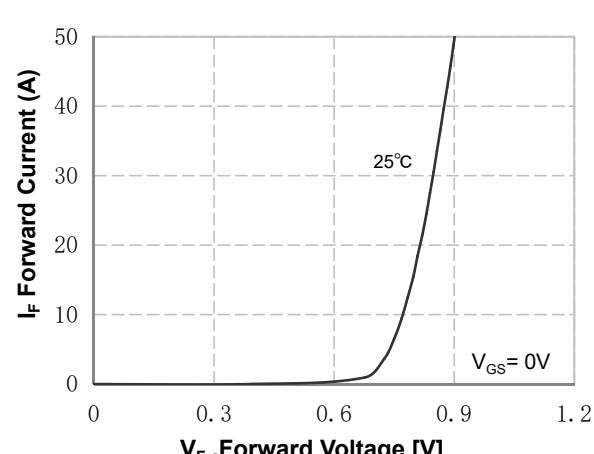


Figure 5. Body Diode Forward Voltage Variation with Source Current

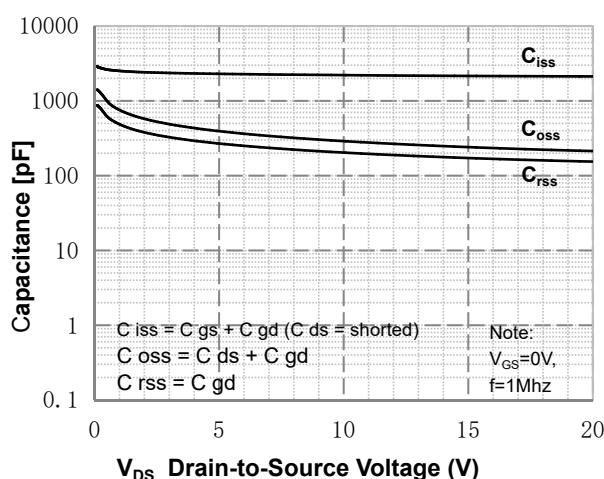


Figure 3. Capacitance Characteristics

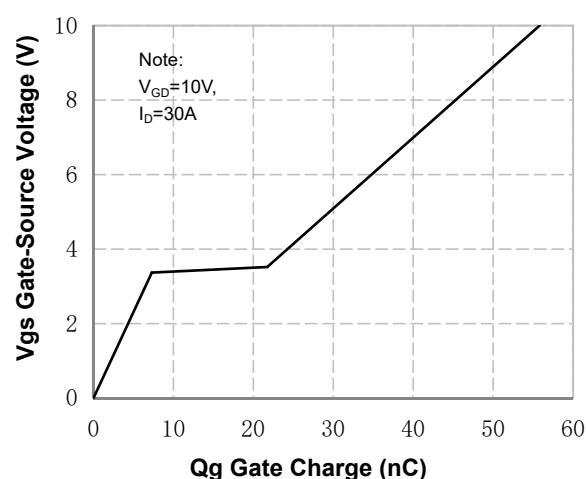


Figure 6. Gate Charge Characteristics

N Channel Typical Characteristics (Continued)

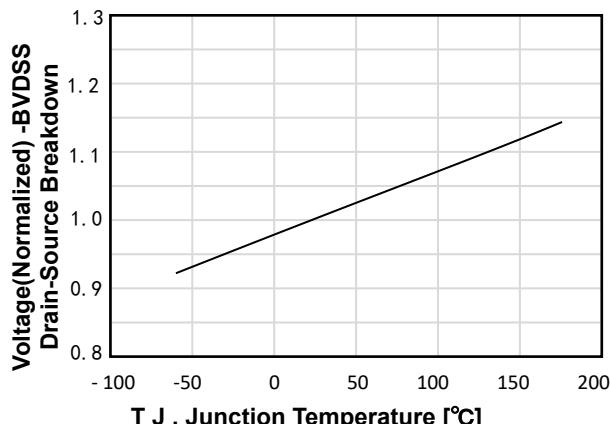


Figure 7. Breakdown Voltage Variation
vs Temperature

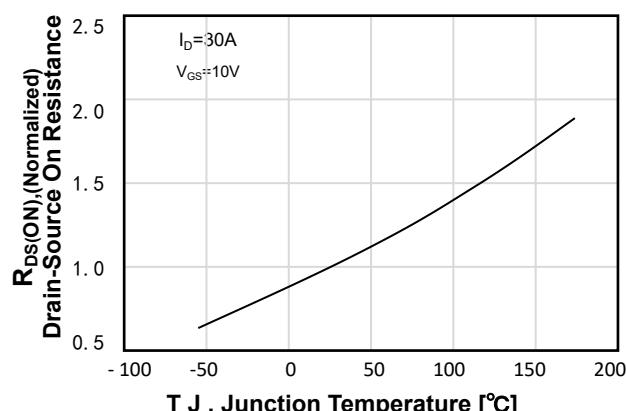


Figure 9. On-Resistance Variation
vs Temperature

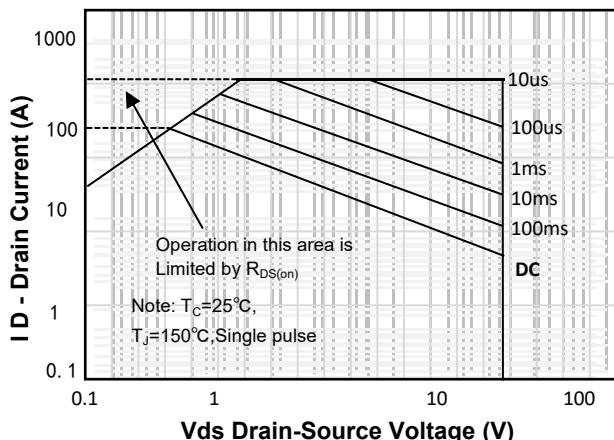


Figure 8. Maximum Safe Operating Area

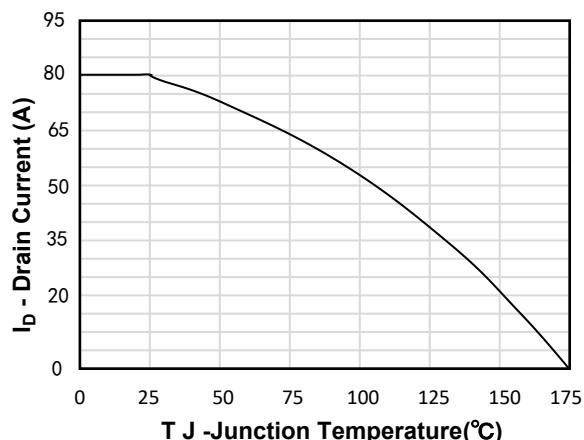


Figure 10. V_{ds} Drain VS Junction
Temperature

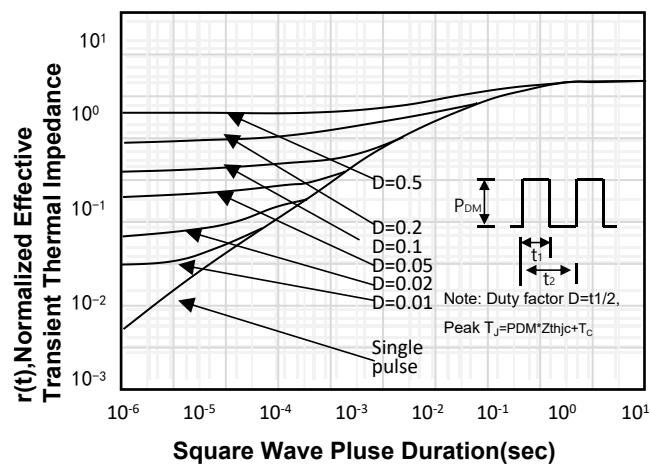
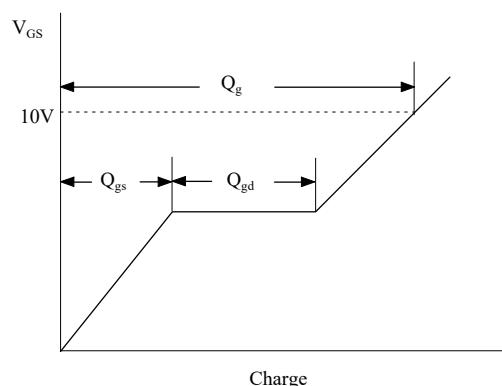
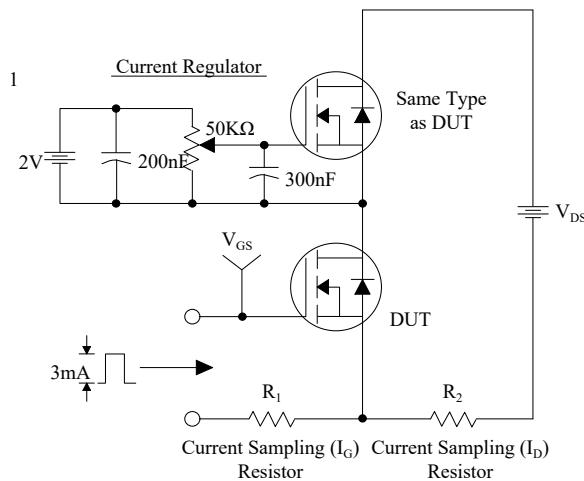


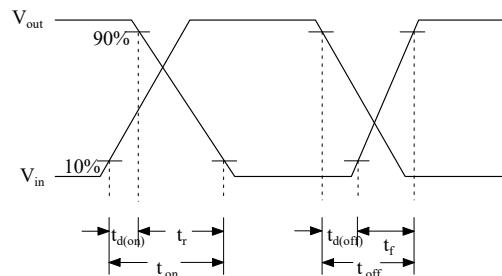
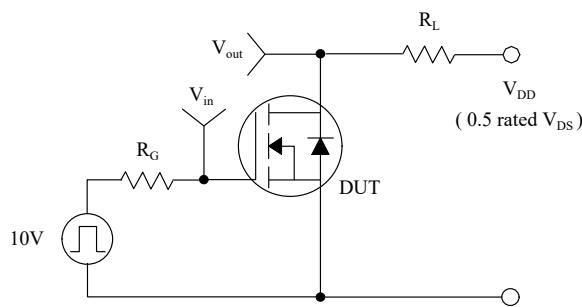
Figure 11. Transient Thermal Response Curve



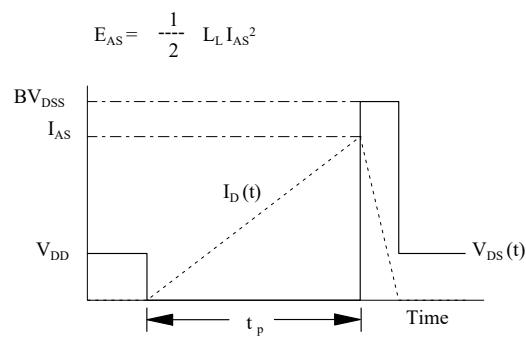
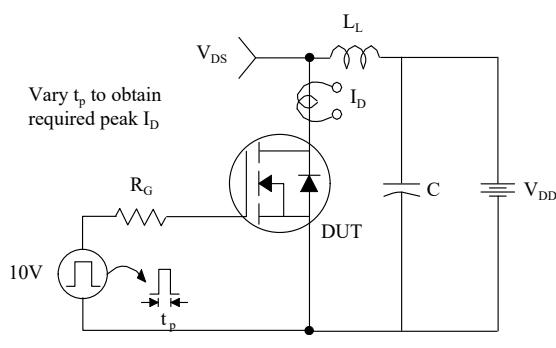
Test Circuit and Waveform



Resistive Switching Test Circuit & Waveforms

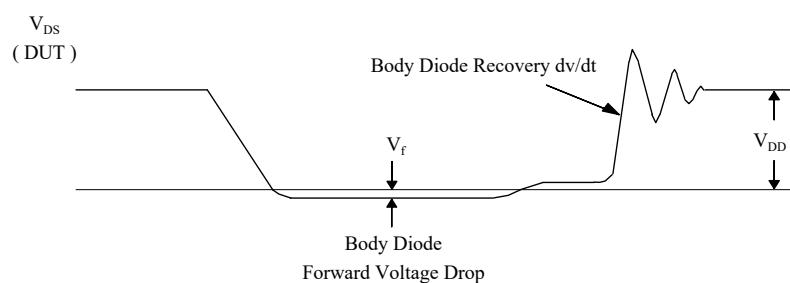
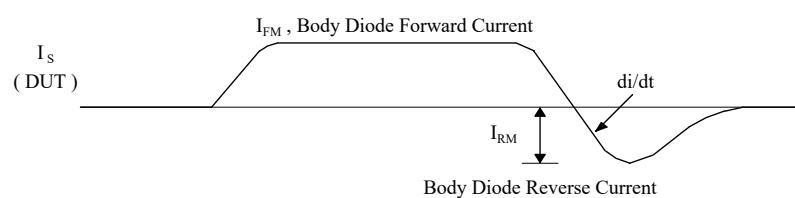
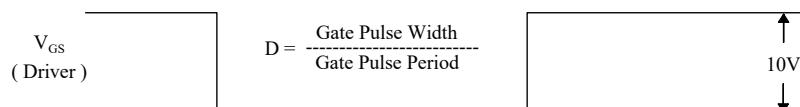
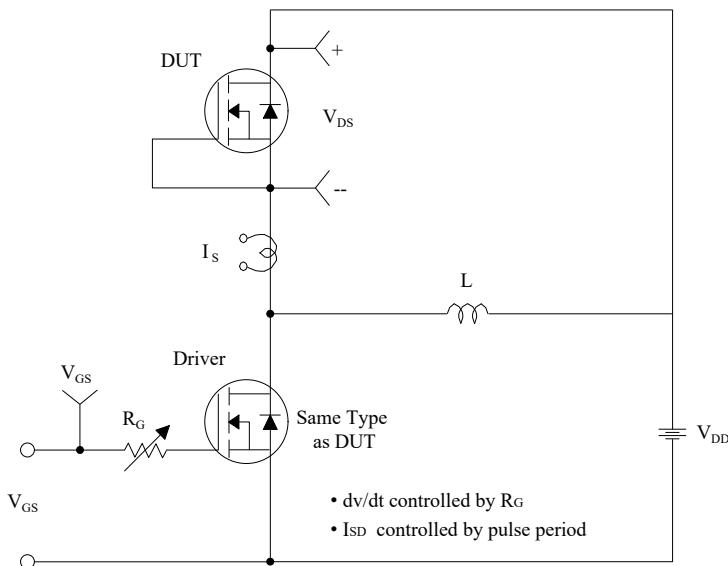


Unclamped Inductive Switching Test Circuit & Waveforms



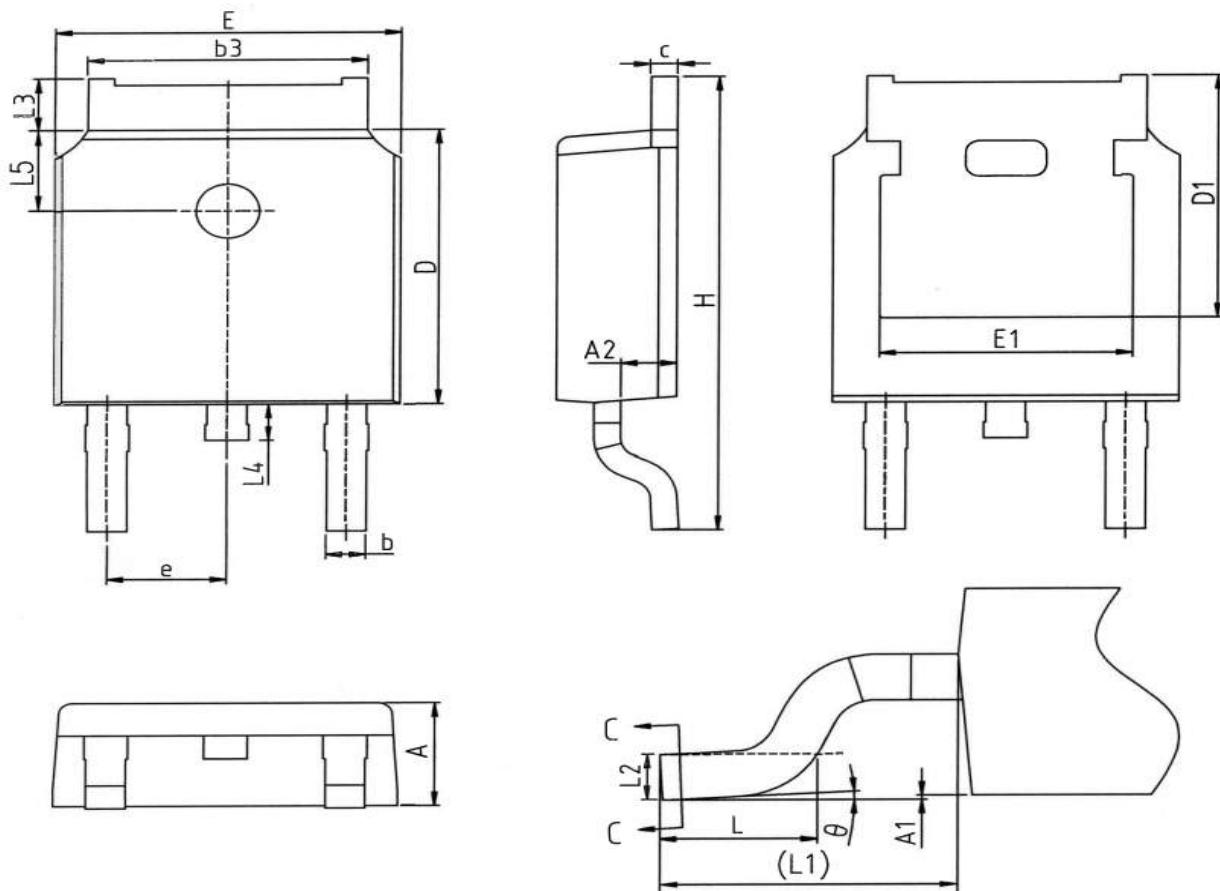


Peak Diode Recovery dv/dt Test Circuit & Waveforms





TO-252 Package Information



SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.00	-	0.12
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°

Customer Service

Sales and Service:

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